



# EMP103B

## DATA SHEET

ISSUED DATE: 02-24-04

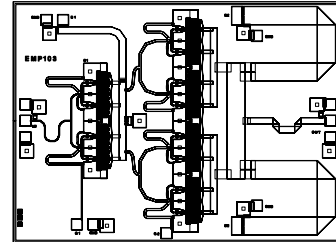
### 6.4 – 8.0 GHz Power Amplifier MMIC

#### FEATURES

- 6.4 – 8.0 GHz Bandwidth
- 33dBm Output Power at 1dB Compression
- 14 dB Typical Power Gain

#### APPLICATIONS

- Point-to-point and point-to-multipoint radio



Dimension: 3000um x 2200um

#### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOL	PARAMETER/TEST CONDITIONS	MIN	TYP	MAX	UNITS
F	Operating Frequency Range	6.4		8.0	GHz
P <sub>1dB</sub>	Output Power at 1dB Gain Compression		32.7		dBm
G <sub>ss</sub>	Small Signal Gain	13	15		dB
IP3	Third Order Intercept		43		dBm
Input RL	Input Return Loss	10	15		dB
Output RL	Output Return Loss		6		dB
I <sub>dd</sub>	Power Supply Current		950		mA
V <sub>dd</sub>	Power Supply Voltage		10		V
R <sub>th</sub>	Thermal Resistance (Au-Sn Eutectic Attach)		7		°C/W

#### ABSOLUTE MAXIMUM RATINGS FOR CONTINUOUS OPERATION<sup>1,2</sup>

SYMBOL	CHARACTERISTIC	VALUE
V <sub>DS</sub>	Drain to Source Voltage	10 V
V <sub>GS</sub>	Gate to Source Voltage	-4 V
I <sub>DD</sub>	Drain Current	I <sub>dss</sub>
I <sub>GSF</sub>	Forward Gate Current	35mA
P <sub>IN</sub>	Input Power	@ 3dB compression
T <sub>CH</sub>	Channel Temperature	150°C
T <sub>STG</sub>	Storage Temperature	-65/150°C
P <sub>T</sub>	Total Power Dissipation	17W

1. Operating the device beyond any of the above rating may result in permanent damage.

2. Bias conditions must also satisfy the following equation  $V_{DS} \cdot I_{DS} < (T_{CH} - T_{HS})/R_{TH}$ ; where T<sub>HS</sub> = ambient temperature



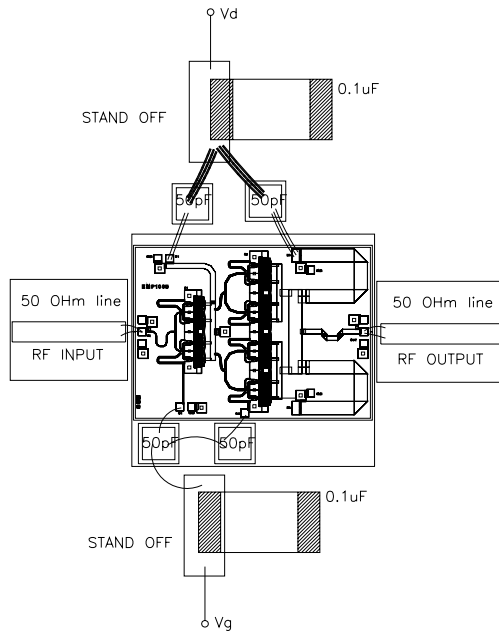
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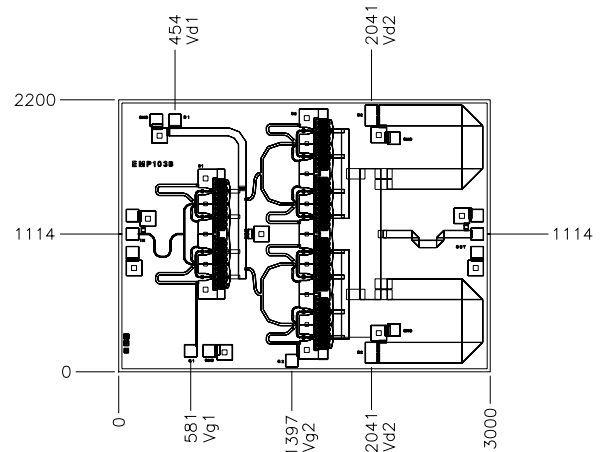
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#### ASSEMBLY DRAWING

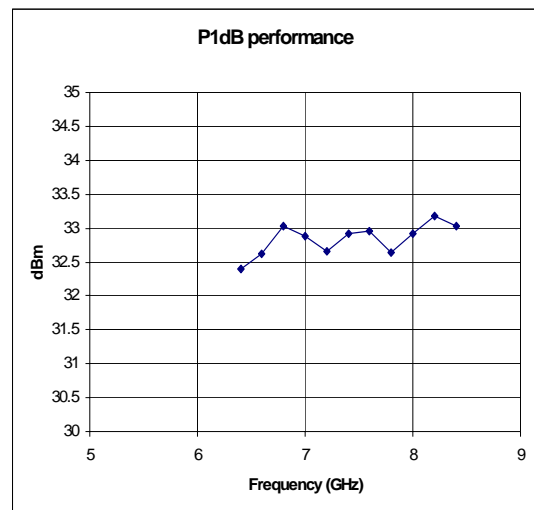
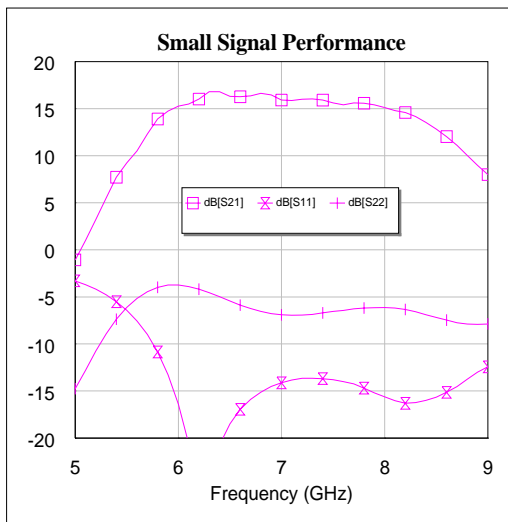


#### CHIP OUTLINE



Chip size: 3000x2200microns  
 Chip thickness: 75 ± 13 microns  
 All Dimensions in Microns

#### TYPICAL PERFORMANCE



Data measured @ Vd=10V, Id=950mA